

Full Wafer & Singulated Die / Module Test System

Compact High Power Test and Reliability Verification Solution for Power, Photonics, Logic & Memory Devices



SYSTEM BENEFITS

- **Compact Flexible Solution for High Throughput Reliability Verification and Test**
 - ♦ Capable of testing thousands of die in a single touchdown
 - ♦ Identifies failing logic / memory / photonic die before final package integration
 - ♦ Integrated system with wafer handling and stepping capabilities
 - ♦ High power thermal chuck dual Blade (slot) capability using WaferPakTM contactors or DiePak[®] carriers (for singulated die and modules)
- **Cost-Effective Solution for High Power Wafer/Die/Module Verification and Test**
 - ♦ Up to 8 modules available per Blade:
 - ♦ Universal Channel Modules (UCCM) with up to 2,048 resources (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory for testing of devices with BIST/DFT capabilities
 - ♦ High Voltage Power Channel Modules (HVPCM) with up to 1,024 29V channels
 - ♦ High Current Channel Modules (HCCM) with up to 1,024 2A channels
 - ♦ BiPolar Voltage Channel Modules (BVCM) with up to 1,024 channels from -30V to 40V
 - ♦ Very High Voltage Channel Modules (VHVCM) single channel up to 2,000V
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
 - ♦ Reduces test costs by functionally testing wafers/die/modules during reliability verification
 - ♦ Compatible with industry standard probers and probe cards
 - ♦ Protects devices with individual per channel over-current and over-voltage protection

“Setting the Test Standard for Tomorrow”

CORPORATE HEADQUARTERS

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